**Product Data**

One Component, Heat Curable Silicone Adhesive  
XE13-A1377

XE13-A1377 is a one-component, non-flowable, heat curable silicone adhesive designed for electrical and electronic applications. This product cures with heating in a short period of time to a tough silicone elastomer.

**KEY FEATURES**
- Non-flowable consistency
- Easy to use; one component system
- Heat accelerated cure
- Primerless adhesion to many substrates - Plastics, Metals, Ceramics and Glass
- Non-corrosive to metals
- Excellent high and low temperature resistance

**TYPICAL APPLICATIONS**
- Adhesive and sealing for hybrid ICs, semiconductor modules, communications devices, lighting units, home appliance assemblies and etc

**TYPICAL PROPERTY DATA**

<table>
<thead>
<tr>
<th>UNCURED PROPERTIES</th>
<th>CURED PROPERTIES (0.5hr @150°C)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Appearance</td>
<td>Translucent, non-flowable</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Property</th>
<th>Uncured</th>
<th>Cured (0.5hr @150°C)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Appearance</td>
<td>Translucent elastic rubber</td>
<td></td>
</tr>
<tr>
<td>Specific gravity (23°C)</td>
<td>1.10</td>
<td></td>
</tr>
<tr>
<td>Hardness (Type A)</td>
<td>56</td>
<td></td>
</tr>
<tr>
<td>Tensile strength (MPa)</td>
<td>3.9 (40)</td>
<td>2.6 (26)</td>
</tr>
<tr>
<td>Elongation (%)</td>
<td>100</td>
<td></td>
</tr>
<tr>
<td>Adhesive strength (MPa)</td>
<td>2.6 (26)</td>
<td></td>
</tr>
<tr>
<td>Volume resistivity (MΩ·m)</td>
<td>2.0X10^7 (2.0X10^15)</td>
<td></td>
</tr>
<tr>
<td>Dielectric strength (kV/mm)</td>
<td>20</td>
<td></td>
</tr>
<tr>
<td>Dielectric constant (60Hz)</td>
<td>2.8</td>
<td></td>
</tr>
<tr>
<td>Dissipation factor (60Hz)</td>
<td>0.001</td>
<td></td>
</tr>
<tr>
<td>Linear expansion (1/K)</td>
<td>2.0X10^-4</td>
<td></td>
</tr>
<tr>
<td>Thermal conductivity (W/(m·K) (cal/(cm·s·°C)))</td>
<td>0.18 (4.2X10^-4)</td>
<td></td>
</tr>
</tbody>
</table>

*Aluminum Lap shear

Typical property data values should not be used as specifications. Assistance and specifications are available by contacting GE Toshiba Silicones Commercial Office.
ADHESION CAPABILITY

Suitable substrates
- Metals: Aluminum, Copper, Ni plate, Stainless steel
- Plastics: PPS, PBT, Epoxy resin, Polyester, Phenolic resin
- Rubbers: Heat cured silicone rubber
- Inorganics: Glass, Ceramics

Not suitable substrates
- Plastics: PP, PE, Fluorocarbon resin
- Rubbers: Silicone RTV, Sulfur vulcanized rubbers, Fluorocarbon rubber

GENERAL INSTRUCTIONS FOR USE AND STORAGE

♦ Materials such as water, sulfur, nitrogen compounds, organic metallic salts, phosphorus compounds, etc. contained in the surface of the substrate can inhibit curing. A sample patch should always be conducted before proceeding to determine compatibility.
♦ Wear eye protection and protective gloves at all times when working with this product.
♦ Maintain adequate ventilation in the work area at all times.
♦ Keep out of the reach of children.
♦ Store at cold temperature (0~10°C) to prevent a viscosity increase.
♦ When returning to room temperature, allow the contents to return to room temperature before opening the container to avoid condensation.
♦ All parts should be as clean and dry as possible prior to application.
♦ Keep out of the reach of children.

PACKAGING

♦ 333ml cartridge available in cases of 50 (5 boxes of 10 cartridges)

FOR INDUSTRIAL USE ONLY

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